

Microchannel Linear Cellular Materials **Processing of High Conductivity**

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14. ABSTRACT Processing of High Conductivity Microchar completion. ! Quality of honeycomb extrus alloys from direct oxide reduction can appre efficiency heat exchangers appear feasible to been demonstrated.	ion has in oach thos	nproved dramatically e of conventionally propertionally	and defects have rocessed alloys	ve been minimized .! Due to low pres	l.! Metallurgical properties of sure drops and thin walls, high					
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Acknowledgements

Honeycomb Structures for Thermal Dissipation Systems



ONR Grant N0014-99-1-0852

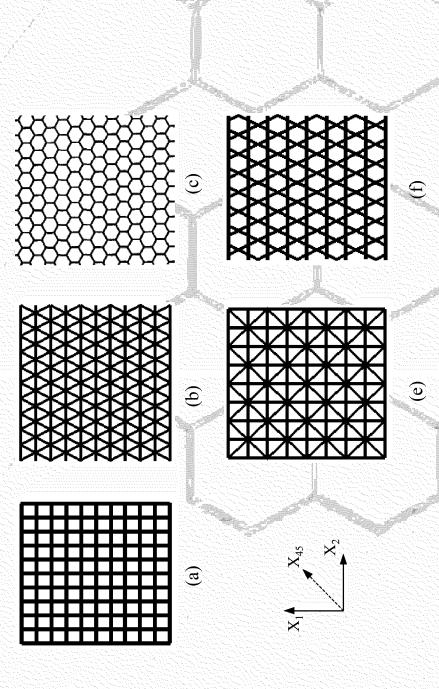
Project Monitor - Dr. Steven Fishman

Linear Cellular Alloys for Structural Applications



Project Monitor - Dr. Leo Christodoulou

Honeycombs with Various Cell Types

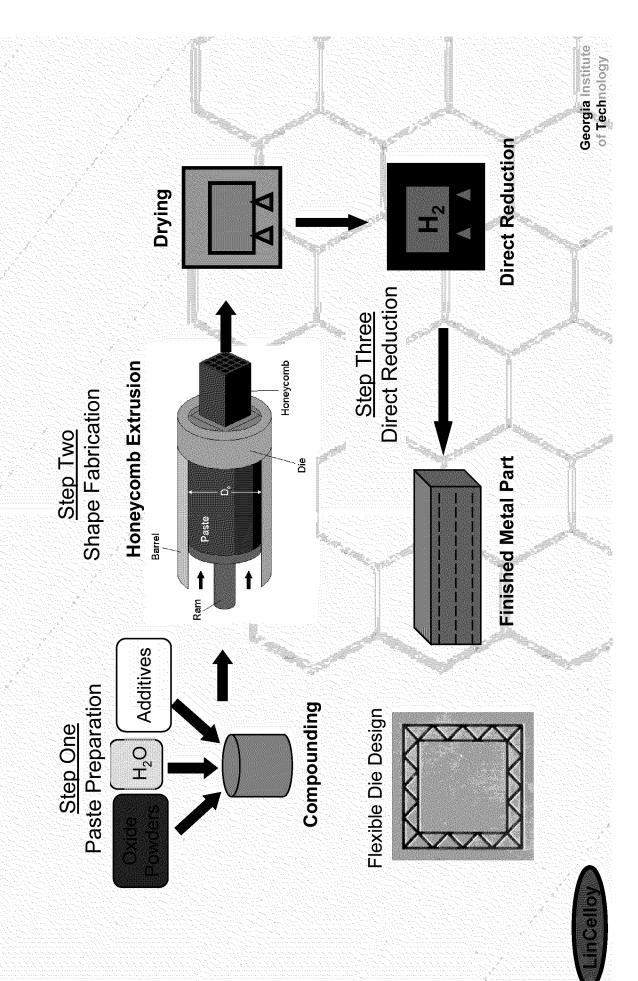


(a) square; (b) triangle; (c) hexagonal; (d) mixed triangle and square; (e) kagome



Oxide Powders Transformed into Metal Linear Cell Structures





Material Compositions

from Fe₃O₄, NiO, Co₃O₄, MoO₃, TiH₂ Reduction = Hydrogen at 1350 °C Fe 18Ni 12Co 4Mo 1.5 Ti Maraging Steels

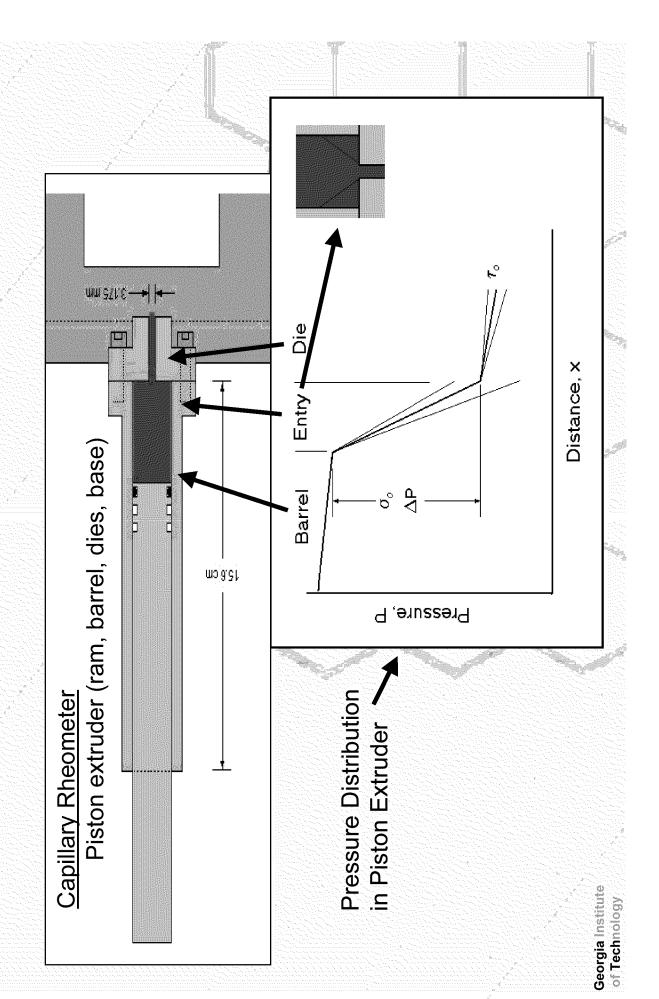
- 22Cr 55Ni 12Co 9Mo from Cr₂O₃, NiO, Co₃O₄, MoO₃ Ni Alloy - "617"
- Cu, Cu 1Ni, Cu 3Ni, Cu 8Ni, Cu 3Ag from Cu₂O, NiO, AgO • Copper
- Inconel reduction process ("718") *

68NiO + 27.8Cr₂O₃ + 25.7Fe₂O₃ + 7.3Nb₂O₅ + 4.5MoO₃

$$\frac{H_2}{}$$
 > 53.4Ni 19Cr 18Fe 5.1Nb 3Mo + 34.8H₂O

*Weight Ratios

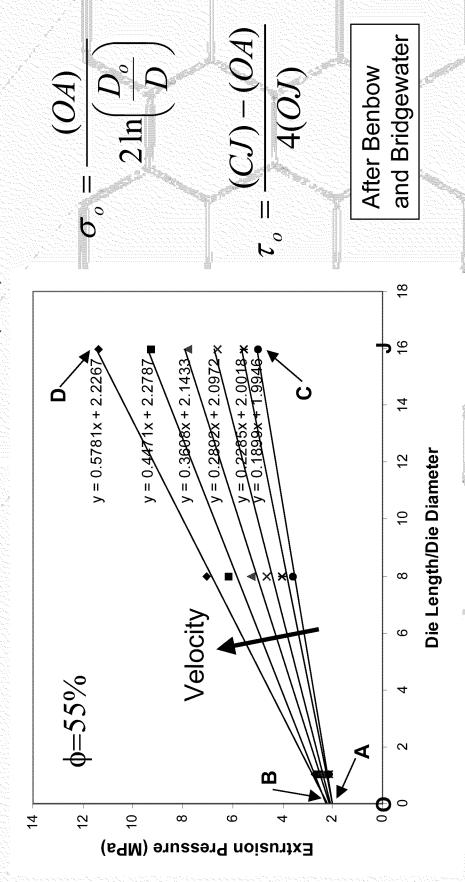
Paste Characterization



Paste Characterization

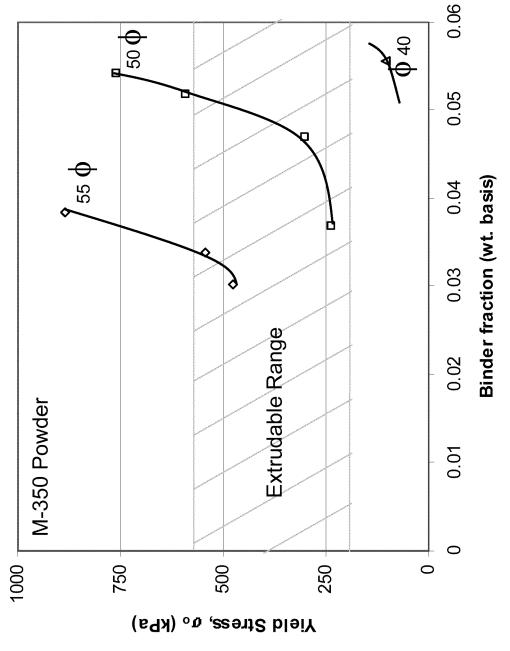
Paste Yield Stress, σ_o , and Wall Shear Stress, τ_o .

$$P = 2(\sigma_o + \alpha V) \ln \left(\frac{D_o}{D} \right) + 4(\tau_o + \beta V) \left(\frac{L}{D} \right)$$



Effect of Binder and Solids Content, **♦**. Paste Characterization

By varying binder and solids content, optimum plasticity coupled with minimum drying shrinkage and reasonable green strength can be achieved while keeping paste yield strength in the extrudable range.



Linear Cellular Die Design

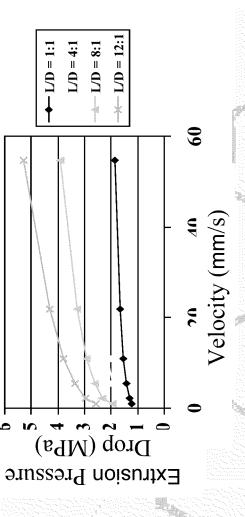
- Extrusion pressure is dependent on:
- Extrudate velocity
- Paste rheology
- Pressure drops result from:
- Change in die area

$$P = (\sigma_o + \alpha V) \ln(A_o / A)$$

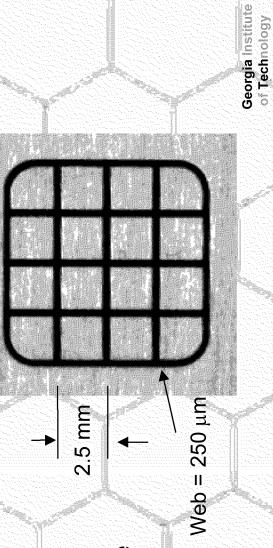
Shear stresses from die wall

$$P = (\tau_o + \beta V)(ML \setminus A)$$

 Utilizing these relationships, predictions for pressure drops across honeycomb dies can be made.



Honeycomb die for rheometer:



Linear Cellular Die Design

Square Cell Die Parameters/ Pressure Drop Modeling

 $D_c = 1.0$ " reduction in barrel to entry holes P₁ = pressure drop from area

P₃ = pressure drop from area P_2 = pressure drop from flow through holes

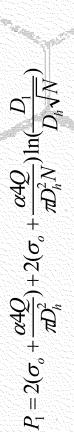
 $L_1 = 0.625$ "

√ariable

P₄ = pressure drop from flow reduction in holes to slots

through die slots

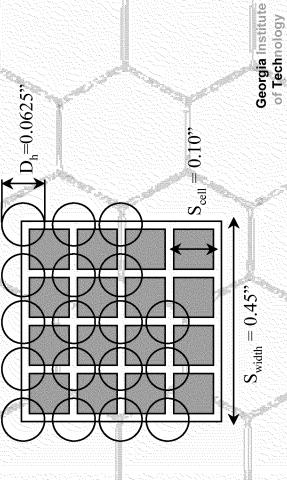




$$P_2 = 4(\tau_o + \frac{\beta 4Q}{\pi D_h^2 N)} \left(\frac{L}{D_h}\right)$$

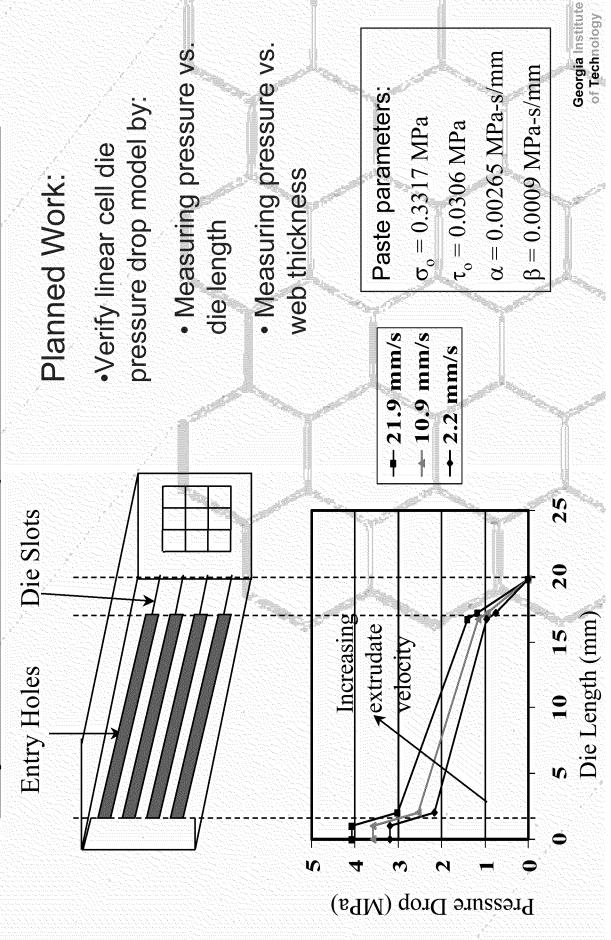
$$P_3 = (\sigma_o + \frac{\alpha Q}{A_v}) \ln(\frac{A_n}{A_v})$$

$$P_4 = 4(\tau_o + \frac{\partial Q}{A_s})(\frac{ML_2}{A_s})$$

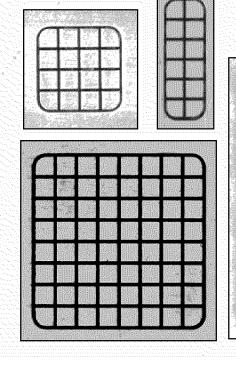


Linear Cellular Die Design

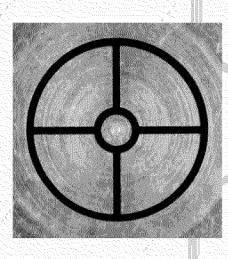
Projected Pressure Drops In Linear Cellular Dies



Linear Cell Extrusion Dies Designed at Georgia Tech

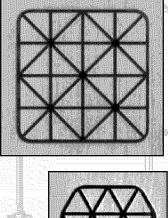


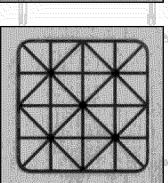
Cell Size = 2.5 mm for Square Cells

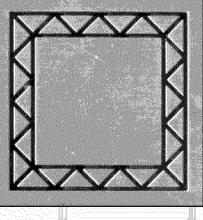


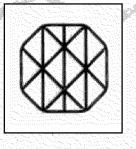
All Die Sizes Are Proportional

← 20 mm



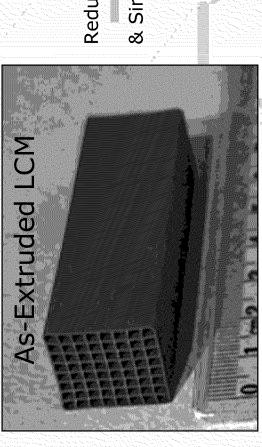






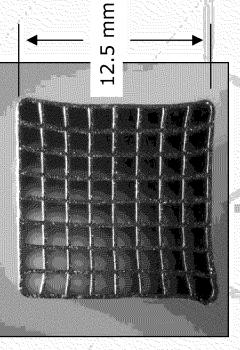


Square Cell, 8X8, Maraging Steel LCM



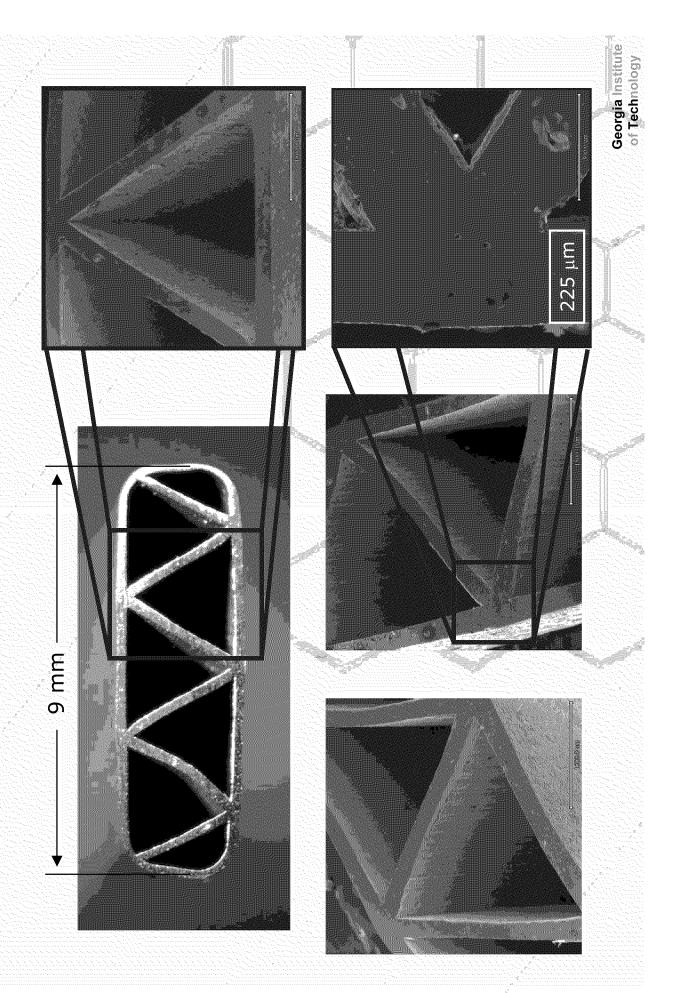
Reduction

& Sintering



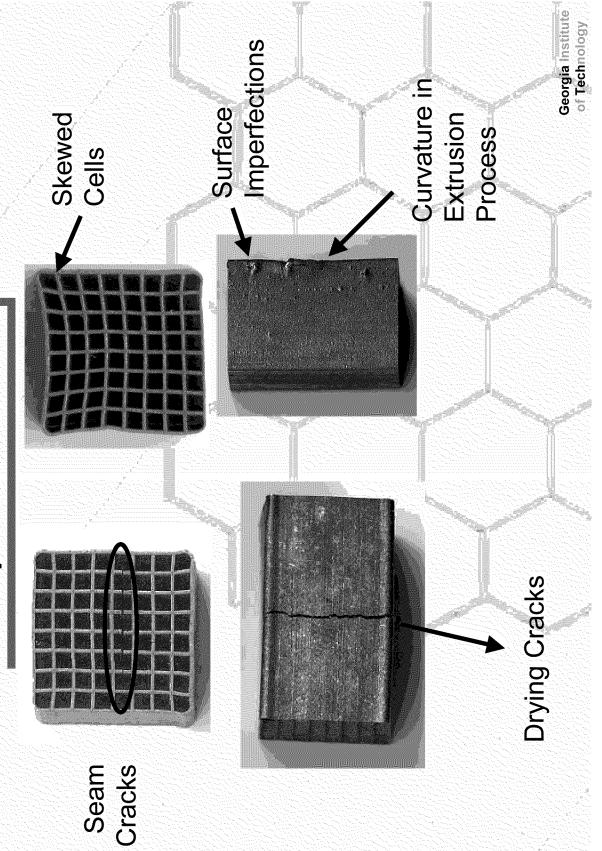
SEM Micrograph Front Lighting

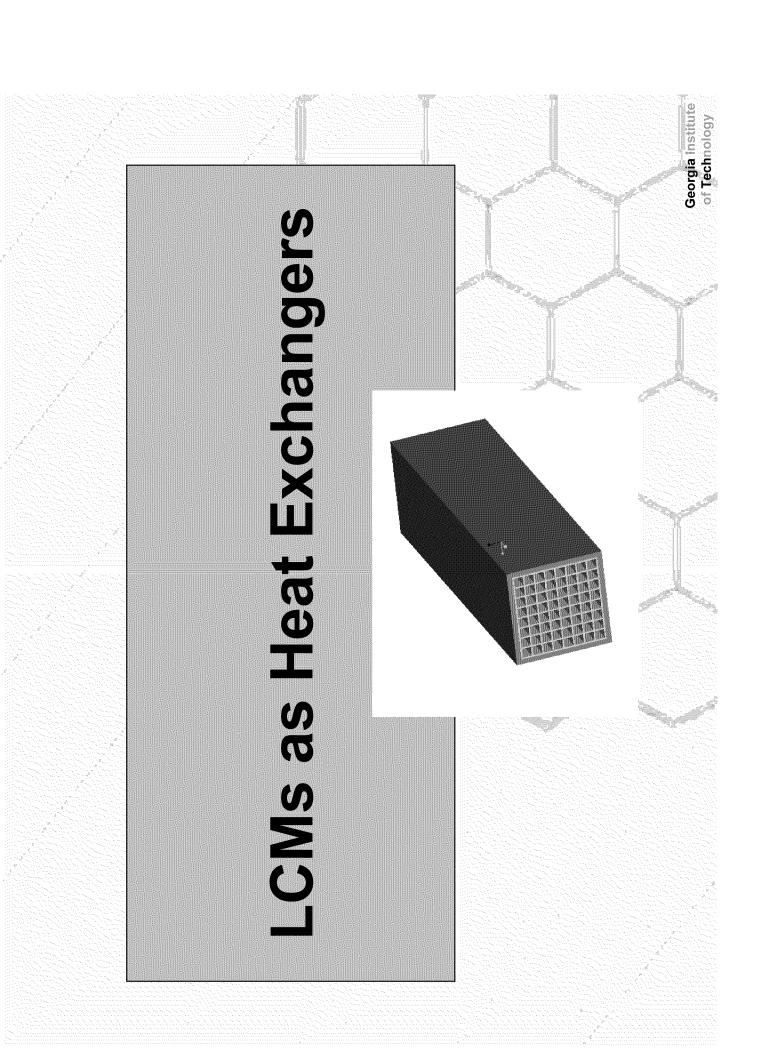
Back Lighting



Compression Behavior of LCAs

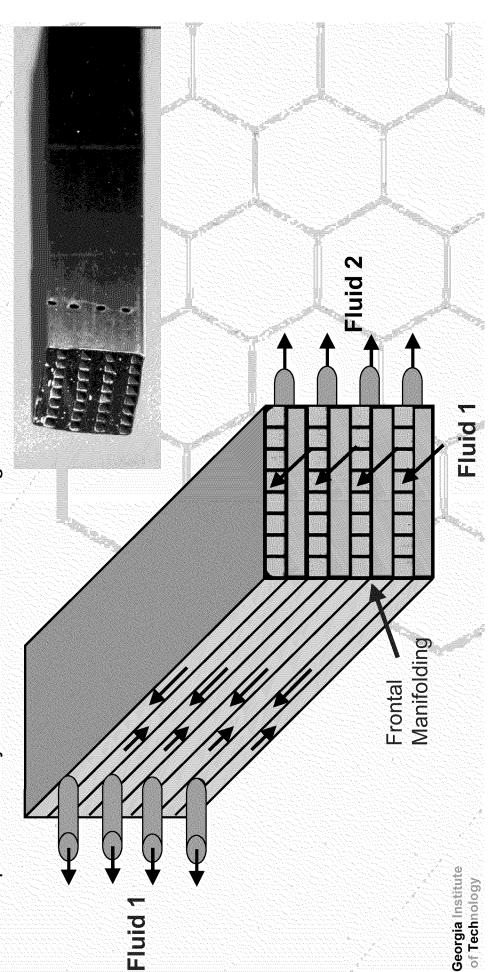
LCA Specimen Defects





Counter Current Heat Exchanger

alternate rows of cells are plugged at one end and connecting holes are drilled in Counter current flow of two fluids on alternating rows is easily manifolded. When opposite rows on the other end and drilling exit holes near the front face. This alternating rows. The opposite flow pattern is provided for fluid 2 by plugging the same cells at the opposite end, flow paths are provided for fluid 1 on permits easily fabricated frontal manifolding for flow control.

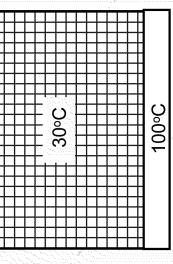


Northrop Grumman
Prototype Heat
Exchanger for **Electronic Cooling** Liquid Flow Square Cell Maraging Steel Channels 2×12 cell Air Flow Georgia Institute of Technology

Forced Air CPU Cooling - Design

Conditions:

50 X 64 mm inlet, 79 mm length Input Air = 30°C, Spreader = 100°C Max pressure Drop = 0.06 in. H₂O Max Air Flow = 12 CFM Cell Wall Conductivity = 165 W/m-K



Ideal Isothermal Q(W), 365 R(°C/W), 0.19 J(W/cm²), 92 T = 78 μm C = 2.6 mm

> Q(W), 286-317 R(°C/W), 0.24-0.22 J(W/cm²), 72-79 T = 440 µm C = 4.0 mm

Proprietary

Proprietary

Q(W), 306-340 R(°C/W), 0.23-0.21 J(W/cm²), 79-72 T = 272 µm C = 3.4 mm

Proprietary

R(°C/W), 0.22-0.20

Q(W), 324-350

J(W/cm²), 81-88

T = 204 μm C = 3.4 mm

Q(W), 332-354 R(°C/W), 0.21-0.20 J(W/cm²), 83-89 T=170 µm

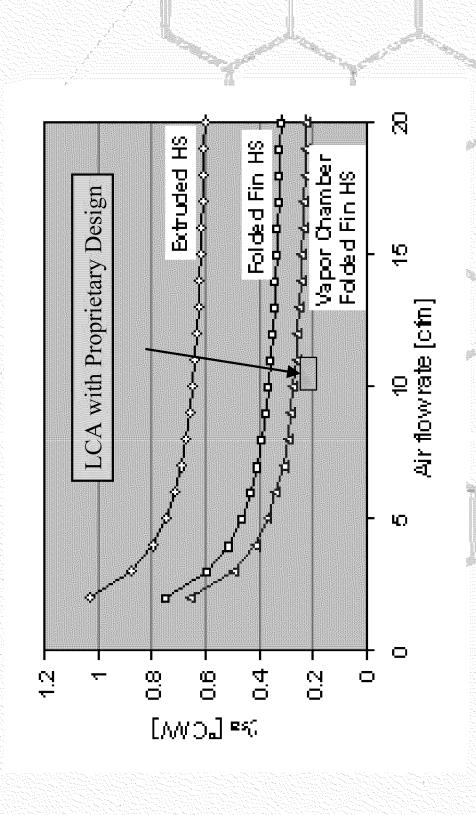
Proprietary

C = 3.4 mm

Lower bound solution for optimized LCA geometry / Upper bound isothermal solution

Forced Air CPU Cooling

Comparison of Thermal Cooling Solutions: Thermal Resistance vs. Flow Rate

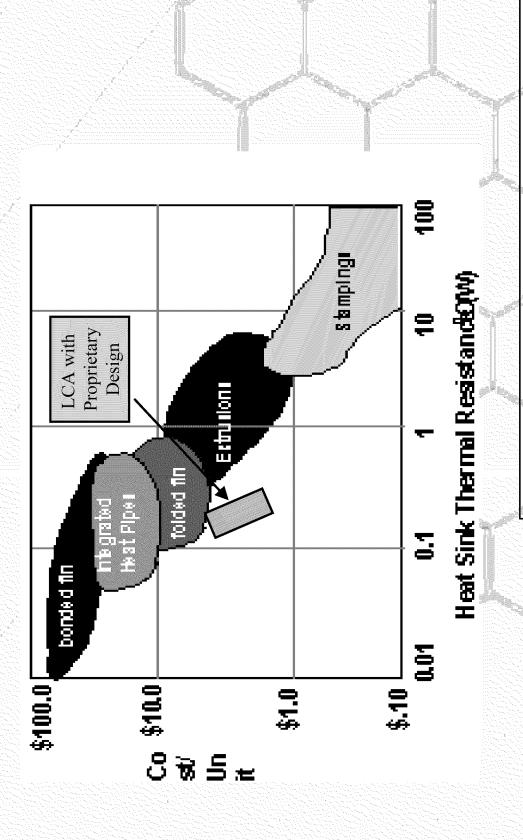


Original Source of Chart: "Thermal Performance Challenges from Silicon to Systems",

R. Viswanath et al., Intel Technology Journal, 3Q 2000

Forced Air CPU Cooling

Comparison of Thermal Cooling Solutions: Unit Cost vs. Thermal Resistance



Original Source of Chart:

"Thermal Performance Challenges from Silicon to Systems", R. Viswanath et al., Intel Technology Journal, 3Q 2000

Basic Issues - Heat Sinks

$$\alpha = \frac{\text{total surface area}}{\text{total volume}}$$

e.g., square cells
$$\rightarrow \alpha \approx \frac{4}{d}$$

for small t/d.

Simple for LCAs, controlled by die design, paste rheology, and processing limitations

$$\frac{\rho}{d} \Rightarrow \frac{2t}{d} = \frac{2t}{d} = \frac{t}{d} = \frac{2t}{d}$$
 For low density

α values are much higher for same characteristic dimension of LCAs than for open cell foams

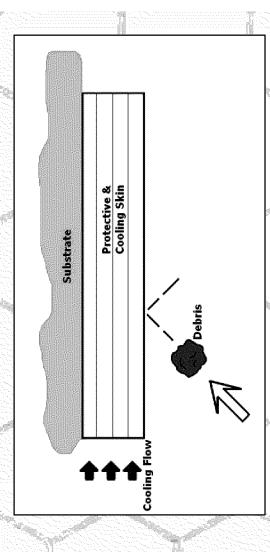
- Laminar (or transition) flow dominates for air cooling; simple pipe friction occurs at Re in the 100-300 range - but this is not a classical random porous & heat transfer coefficient relations exist. Note: in porous media, transition
- Can heat sink dissipate 50-100 W/cm²?
- Strategies: (a) thermal gradients, (b) cell morphology, (c) hybrid heat sinks

Some Applications

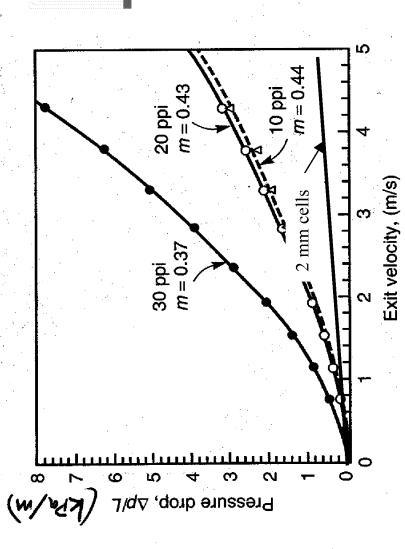
- Heat Removal
- Computer chips

Heat Source

- Recapture of Lost Heat
- Engines
- Structural / Heat Transfer
- Actively cooled skins



Laminar Flow Pressure Drop



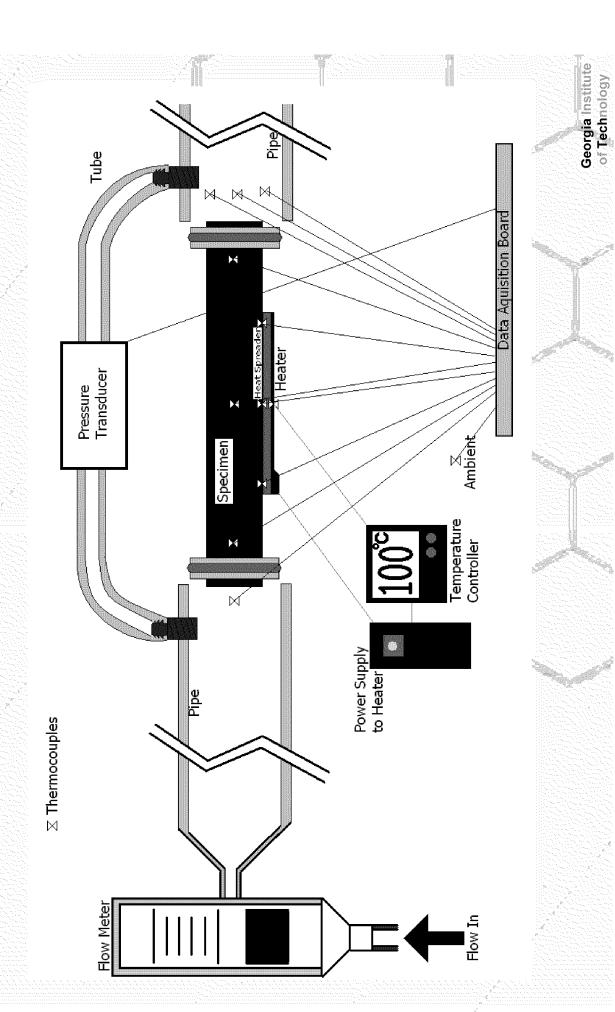
general relation) $Re = \frac{\rho Vd}{\rho}$ $\frac{\Delta P}{\rho \, g} =$

$$\frac{\Delta P}{\rho g} = f \frac{L}{d} \frac{V^2}{2g} = \frac{57}{Re} \frac{L}{d} \frac{V^2}{2g}, \quad \Rightarrow \Delta P = \frac{28.5 \mu L V}{d^2}$$

laminar flow in square duct

Georgia Institute

Experimental Apparatus

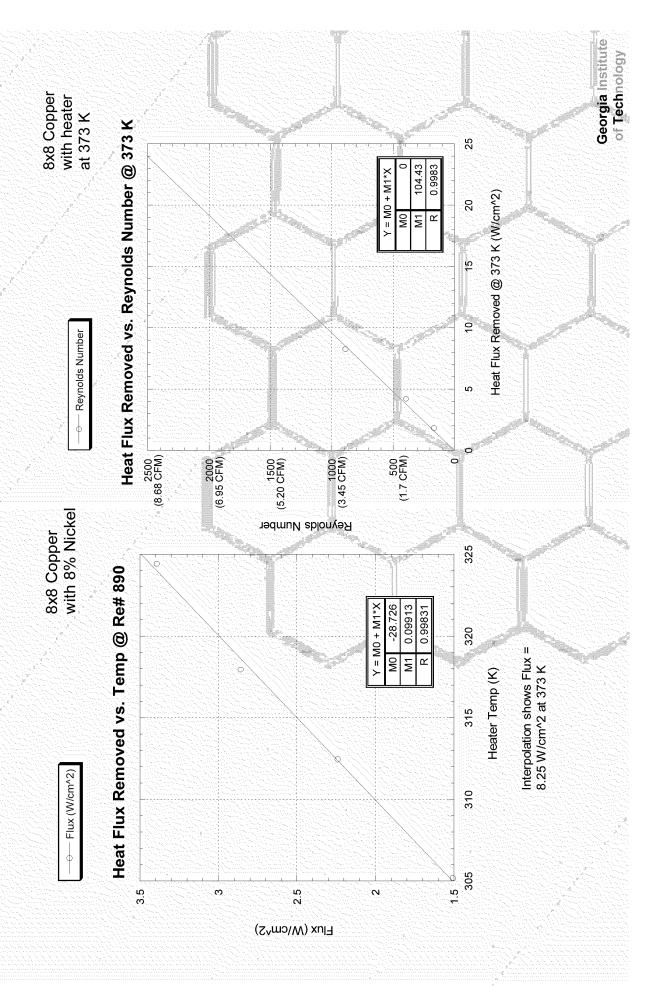


Georgia Institute of Technology $Re_d = 2000$ Pressure Drop vs. Flow and Head Loss 8x8 Maraging Steel LCA Length = 11.2 cm, d = 1.37 mm, t = 0.25 mm K = 1.2 Flow (CFM) Laminar + K*rho*V^2/2 ····· Laminar Solution Experimental 1200 1000 1400 800 9 200 400 la min ar duct Pressure Drop (Pa) $\Delta P_{\rm LCA} = \Delta P$ $Re_{d} = 2400$ 8x8 Maraging Steel LCA Length = 4.36 cm, d = 1.35 mm, t = 0.23 mm K = 1.2 Pressure Drop vs. Flow and Head Loss Flow (CFM) Laminar Solution
Laminar + K*rho*V^2/2 Experimental 0 1400 1200 1000 009 200 400 0 800 Pressure Drop (Pa)

Experiments: LCIM Conductivity

Conductivity (W/m·K)	64.48	130.31	165.52	192.27	248:00		401	52	23	
Conc					i					
						(96		1)		
						a & Dewitt, 1996)		0% Cu, 10% A	.5% Ni)	
Composition (LCM)	8%	3%		5.1%	3 3%	Tabular Values (Incropera & D	Pure Copper	Commercial Bronze(90% Cu, 10% Al)	Constantan(55% Cu, 45% Ni)	
<u>Composi</u>	CuNi 8%	CuNi 3%	5	. CuAg 1%	CuAg 3%	<u> </u>	Pure	Comi	Const	

Experimental Results: 2" heated length



pper and Lower Bound Solutions on Steady Sta Heat Transfer Rates for Square Cell LCMs

Upper:

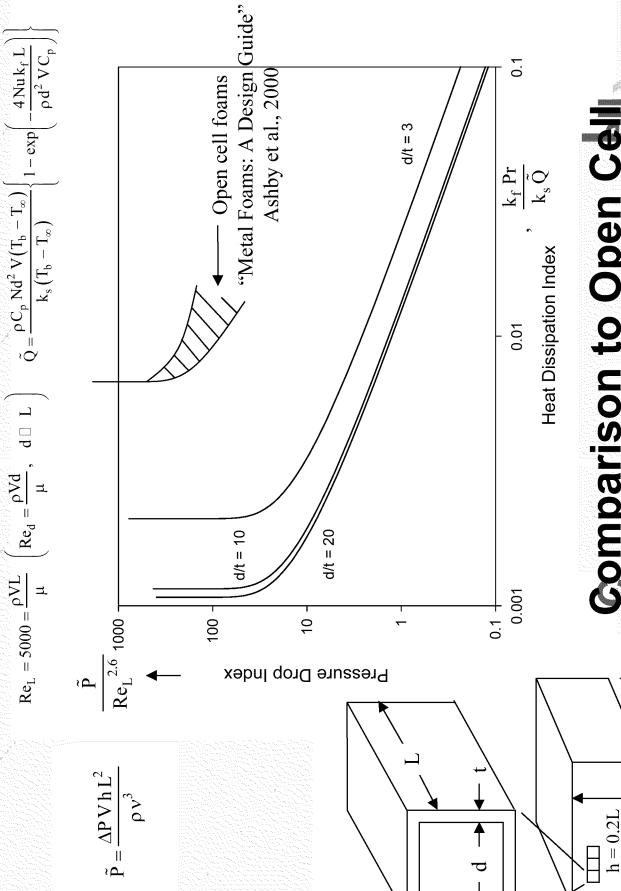
$$q^{isothermal} = \rho \, C_p \,\, Nd^2 \, V \big(T_b - T_\infty \big) \big\{ 1 - exp \big(-\beta \big) \big\}$$

Lower:

$$q^{peripheral} = \rho \, C_p \, Nd^2 \, V \big(T_b - T_\infty \big) \big\{ 1 - \exp(-\beta) \big\} \sqrt{\frac{4}{LCM}} \, \tanh \left\{ \sqrt{\frac{LCM}{4}} \right\} \bigg|_{-\frac{1}{4}}$$

$$q^{base} = \rho \, C_p \; Nd^2 \; V \big(T_b - T_\infty \big) \big\{ 1 - exp \big(-\beta \big) \big\} \sqrt{\frac{1}{4 \, LCM}} \; tanh \big\{ \sqrt{4 \, LCM} \big\}$$

$$Re_L = 5000 = \frac{\rho VL}{\mu} \quad \left(Re_d = \frac{\rho Vd}{\mu}, \quad d \square L \right) \quad \tilde{Q} = \frac{\rho C_p \ Nd^2 \ V(T_b - T_\infty)}{k_s \left(T_b - T_\infty \right)} \left\{ 1 - exp \left(-\frac{4 \ Nu \ k_r L}{\rho d^2 \ VC_p} \right) \right\}$$



Comparison to Open Cell Metal Foams

Georgia Institute

Eptry Length Effects for Square Cell LC**M**家

$$h = Nu \frac{k_f}{d}$$

$$Nu_{m,T} = 0.1222 + 2.8337 \ln\left(\frac{1}{\frac{x}{x}}\right) - 0.8083 \left\{ \ln\left(\frac{1}{\frac{x}{x}}\right) \right\}^2 + 0.1134 \left\{ \ln\left(\frac{1}{\frac{x}{x}}\right) \right\}^3 \qquad x^* = \frac{x}{d\,\mathrm{Re}\,\mathrm{Pr}}$$

$$Nu_{ave} = \frac{1}{L} \int_0^L N_{m,T} \ dx = 2.0197 - 1.8975 \ln \left(\frac{L}{d\,Re\,Pr} \right) - 0.4681 \left\{ \ln \left(\frac{L}{d\,Re\,Pr} \right) \right\}^2 - 0.1134 \left\{ \ln \left(\frac{L}{d\,Re\,Pr} \right) \right\}^3$$

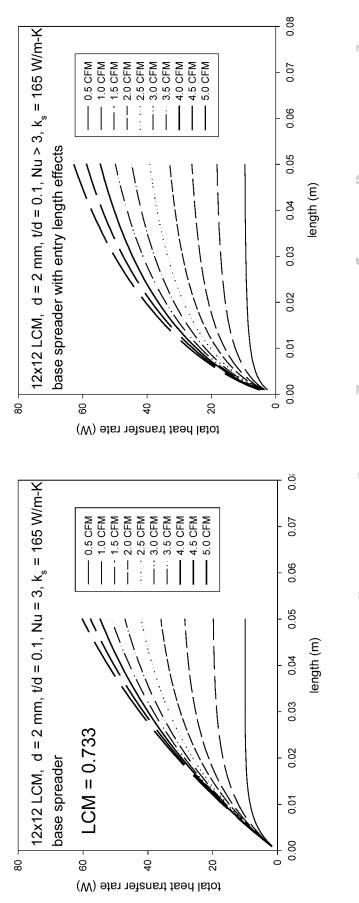
for $\frac{L}{d} \le 0.21128 \text{ Re Pr}$

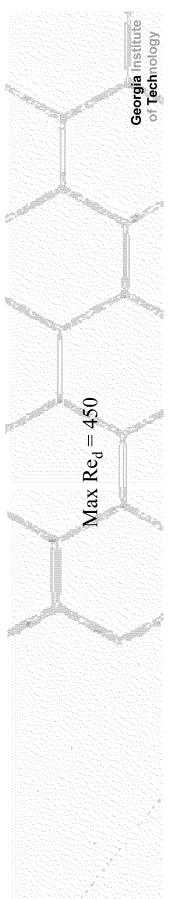
Nu_{ave} = 3 + 0.267 Re Pr
$$\frac{d}{1}$$
 for $\frac{L}{d}$ > 0.21128

for
$$\frac{L}{d} > 0.21128$$
 Re Pr

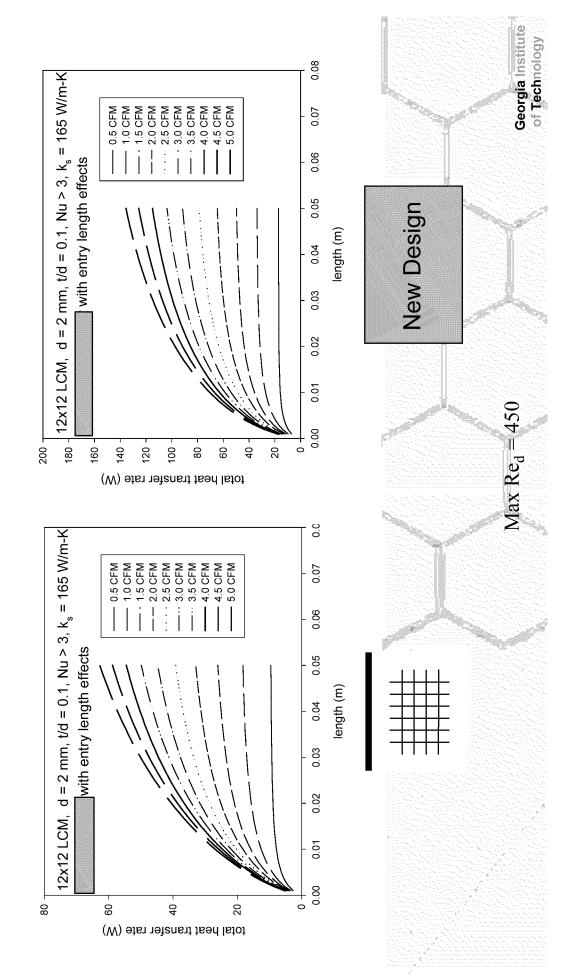
"Advances in Heat Transfer: Laminar Flow Forced Convection in Ducts" by R.K. Shah and A.L. London, Academic Press, NY, 1978 (pg. 220).

Eptry Length Effects for Square Cell LCMs





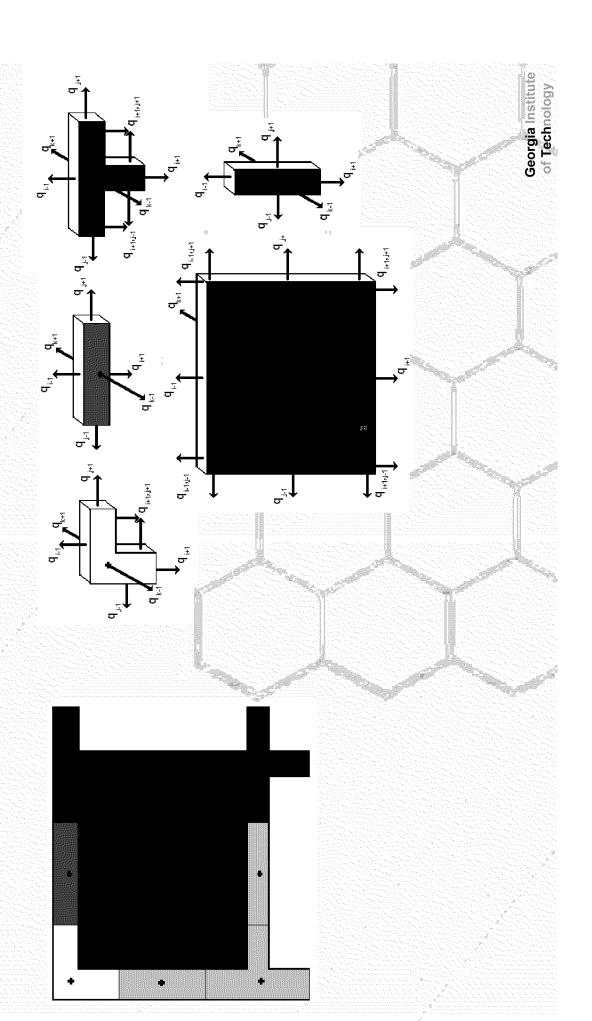
New Design Effects for Square Cell LCMs

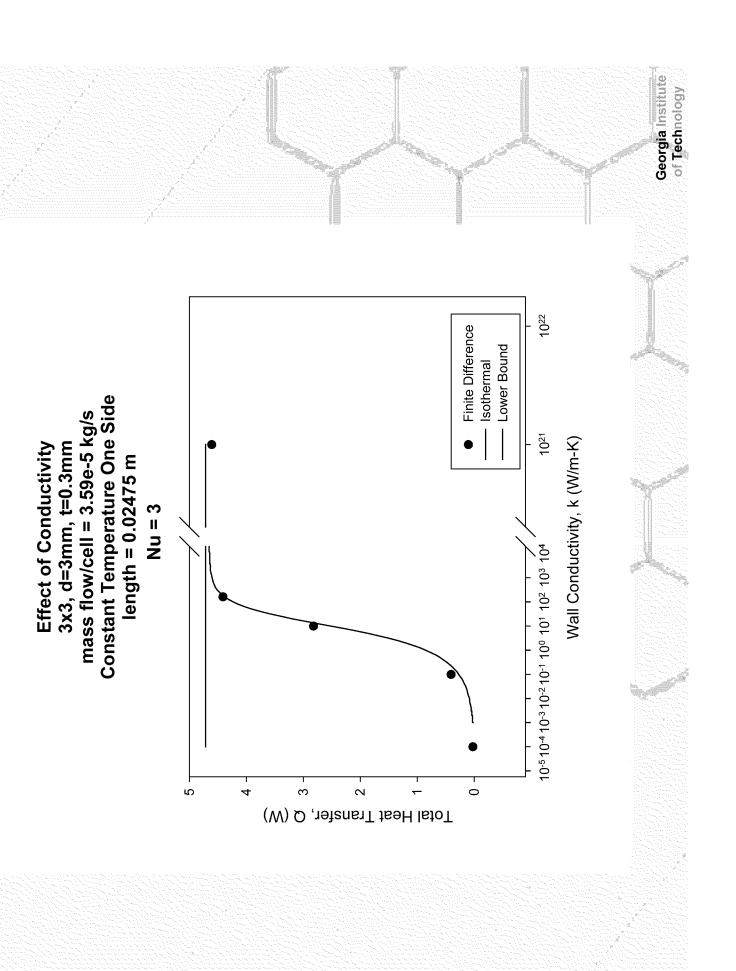


Finite Difference Code

- The following two equations are good for all of the different types of elements
- $-\dot{E}_{in} \dot{E}_{out} + \dot{E}_{generated} = \dot{E}_{stored}$
- $q_{i-1} + q_{i+1} + q_{j-1} + q_{j+1} + q_{k-1} + q_{k+1} = 0$
- Each element interacts with the elements around it by one of three methods of heat transfer
- $-Q = m \cdot c_p \cdot (T_{mean,out} T_{mean,in})$
 - $-Q = h \cdot A_c \cdot (T_{surface} T_{fluid})$
- $-\mathbf{Q} = -\mathbf{k} \cdot \mathbf{A_c} \cdot \Delta \mathbf{T} / \Delta \mathbf{x}$

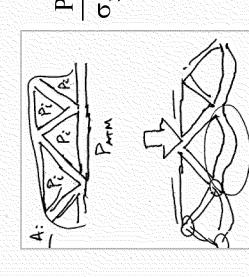
Finite Difference Code





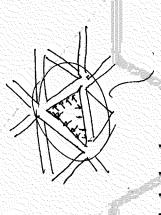
Basic Issues - Heat Sinks

Pressure drop and cell burst overpressure (McDowell, 1999)



$$= \frac{16}{9} \left(\frac{\rho}{\rho_s}\right)^2 \text{ for triangular cells}$$

$$\left(\frac{\rho}{\rho_s}\right)^2 \text{ for square cells}$$

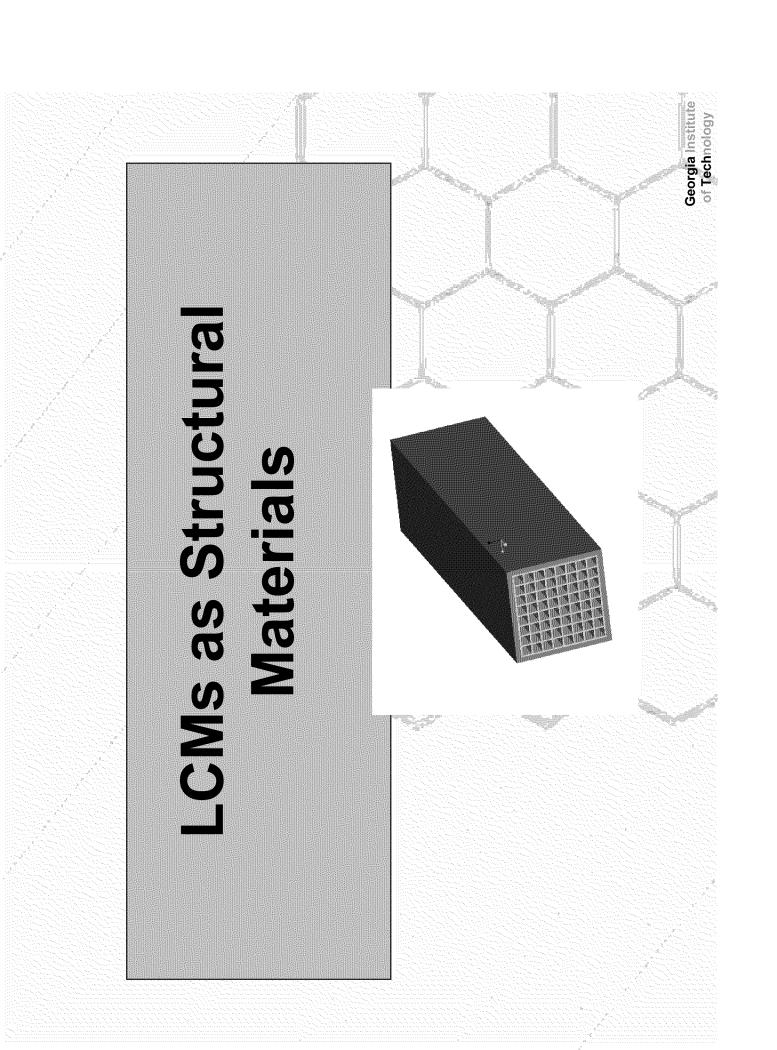


Slightly lower due to shift of neutral axis due to cell wall extension

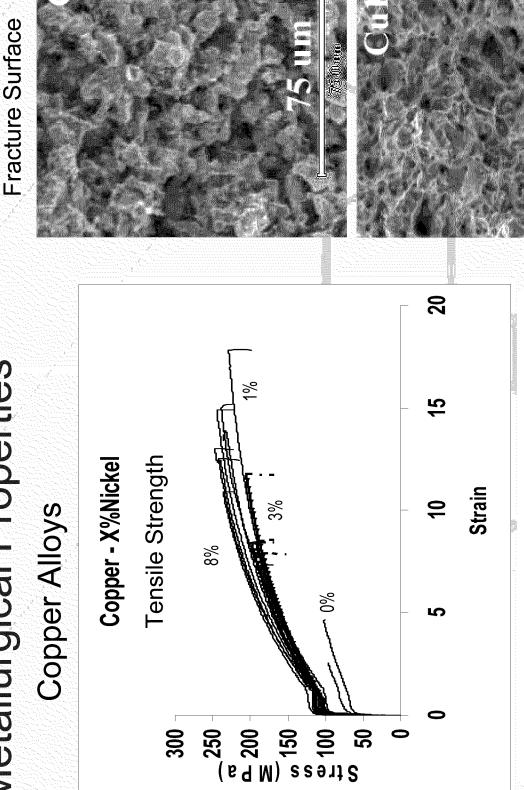
For a relative density of 10%, P_i is approx. 1% of the plastic flow stress,

limited by S_u, i.e.

Al alloys — 300-500 psi Ni alloys — 1000-2000 psi Cu alloys — 200-400 psi



Metallurgical Properties

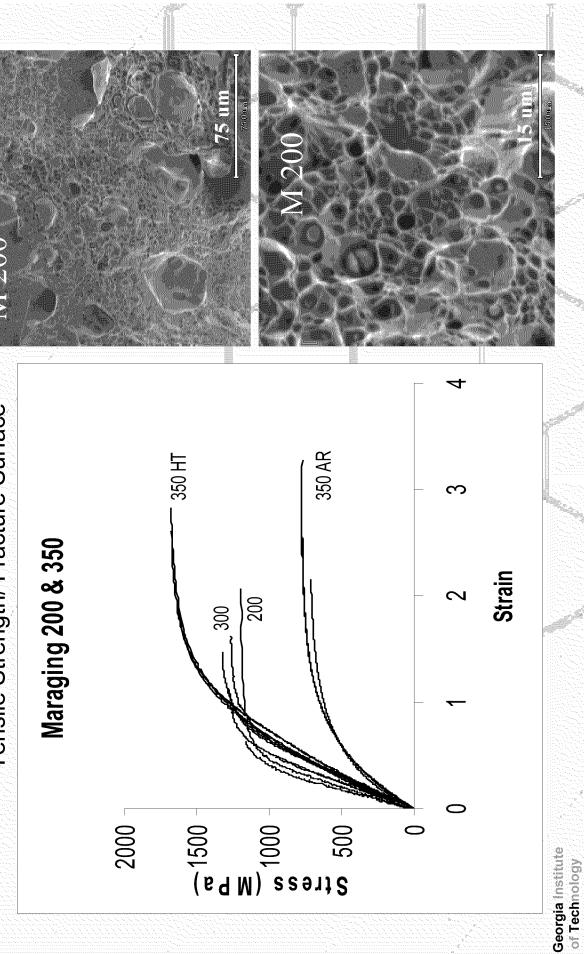


Thickness = 0.56 mm Width = 5.72 mm

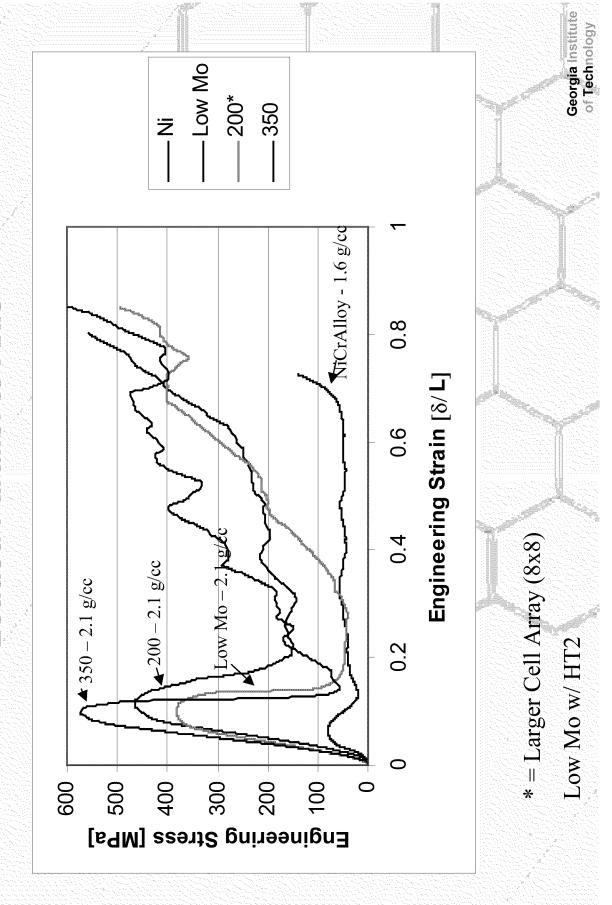
Metallurgical Properties

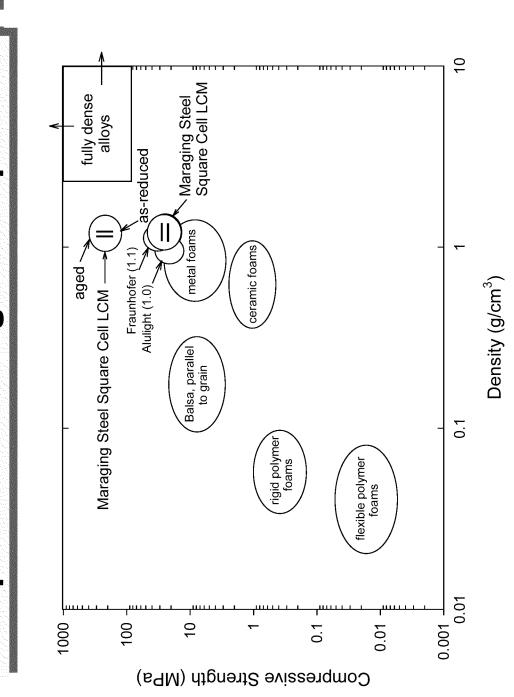
Maraging Steel

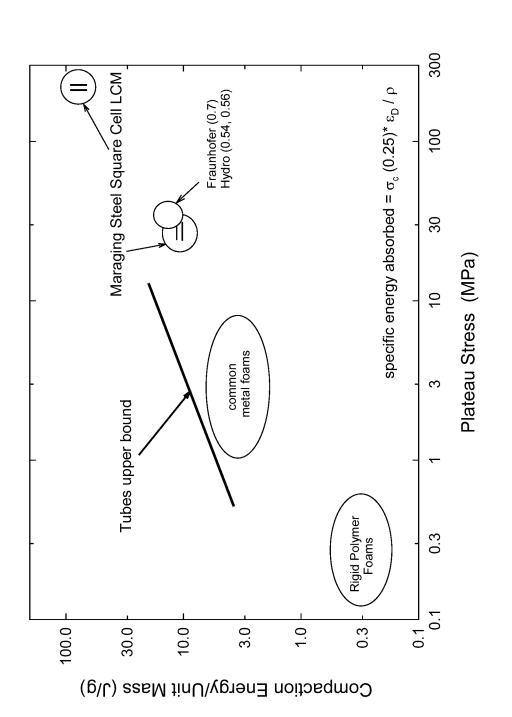
Tensile Strength/ Fracture Surface

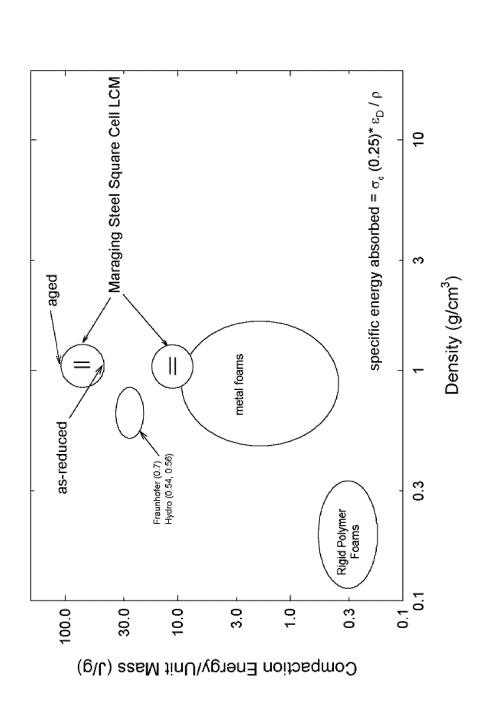


Strength of Square Cell Maraging Steel LCM Loaded Parallel to Axis











CONCLUSIONS

Microchannel Linear Cellular Materials **Processing of High Conductivity**

! Models for paste properties and LCS die designs are nearing completion.

! Quality of honeycomb extrusion has improved dramatically and defects have been minimized. ! Metallurgical properties of alloys from direct oxide reduction can approach those of conventionally processed alloys.

efficiency heat exchangers appear feasible for LCAs in a ! Due to low pressure drops and thin walls, high variety of applications.

! High energy adsorption for LCM-in high strength alloys has been demonstrated.